

No-Clean Solder Wire

Sn99/Ag0.3/Cu0.7, 250 g, 1 mm



FEATURES:

SPECIFICATION:

Alloy	Sn99/Ag0.3/Cu0.7
Flux	B 2.1
Proportion of flux	2.5 %
Solder wire diameter	1 mm
Weight	250 g
Melting point	+217 °C

Art. Nr.

RND 560-00176

